Nordson Test & Inspection to Showcase Advanced Semiconductor Technologies at SEMICON West 2024

Minneapolis, Minnesota — June 2024 — Nordson TEST & INSPECTION today announced plans to exhibit at SEMICON West 2024, scheduled to take place July 9-11 at the Moscone Center in San Francisco, California. Visitors to booth 1233 will have the opportunity to see demonstrations of Nordson's WaferSense® semiconductor sensors, Quadra Pro™ Manual X-Ray System (MXI), and Gen 7™ Acoustic Micro Imaging (AMI) system. Additionally, the innovative SpinSAM™ AMI system will be unveiled in a video presentation for the first time at the show.

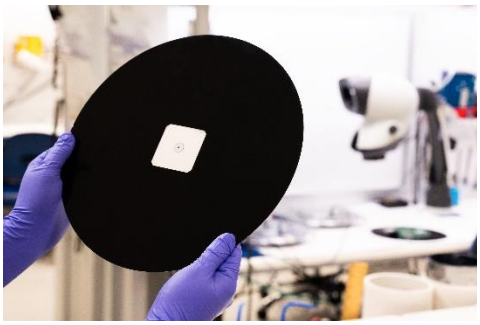
The new SpinSAM AMI system delivers industry-leading throughput with unparalleled sensitivity for accurately locating defects in wafer based assemblies. The SpinSAM's innovative spin scanning method scans up to 4 (300mm) wafers simultaneously at 41 wafers per hour, with best-in-class defect capture and image quality.

With 4 matched waterfall transducers, the system was meticulously engineered to attain full wafer scans in less than 6 minutes. Ideal semiconductor mid-end applications include bonded wafers, Chip-on-Wafer, stacked wafers, MEMS, over-molded wafers and more.

Setting a new industry benchmark for 3D/2D manual inspection in back-end semiconductor applications, the Quadra 7 Pro MXI system revolutionizes the inspection experience with its Onyx® detector technology. This advancement ensures exceptional image clarity and elevated levels of precision and efficiency. The Dual Mode Quadra NT4® tube provides unprecedented flexibility. This innovative technology offers both brightness and resolution modes, enabling operators to seamlessly transition between them according to specific application requirements. This ensures optimal results for a wide range of semiconductor inspection needs.

The Gen7 AMI system powered by C-SAM technology, provides fast and highly accurate inspection for detecting delamination and voiding with the most sophisticated microscope. Ideal for lab analysis and specialized high-resolution applications.

Lastly, for front-end semiconductor tool set-up and maintenance, the WaferSense® ATS2 multi-camera sensor, paired with CyberSpectrum™ software captures offset data (x, y and z) to quickly teach wafer transfer positions in real-time without opening the tool.



Visit Nordson Test & Inspection at booth 1233 to experience the future of semiconductor inspection and metrology technology that improves yields, processes, throughput and productivity.

For more information, visit www.nordson.com/testinspect.

About Nordson TEST & INSPECTION
Nordson TEST & INSPECTION offers its SMT & Semiconductor customers a robust product portfolio, including Acoustic, Optical and both Manual and Automated X-ray Inspection systems, X-ray Component Counting systems and Semiconductor measurement sensors. Nordson TEST & INSPECTION is uniquely positioned to serve its customers with best-in-class precision technologies, passionate sales and support teams, global reach, and unmatched consultative applications expertise.

About Nordson
Nordson Corporation (Nasdaq: NDSN) is an innovative precision technology company that leverages a scalable growth framework through an entrepreneurial, division-led organization to deliver top tier growth with leading margins and returns. The Company's direct sales model and applications expertise serves global customers through a wide variety of critical applications. Its diverse end market exposure includes consumer non-durable, medical, electronics and industrial end markets. Founded in 1954 and headquartered in Westlake, Ohio, the Company has operations and support offices in over 35 countries. Visit Nordson on the web at Www.Nordson.Com, linkedin/Nordson, or Www.Facebook.Com/Nordson.

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